

SLOVENSKI STANDARD SIST EN ISO 11855-3:2021/oprA1:2023

01-marec-2023

Načrtovanje notranjega okolja v stavbah - Vgrajeni sevalni ogrevalni in hladilni sistemi - 3. del: Načrtovanje in dimenzioniranje - Dopolnilo A1 (ISO 11855-3:2021/DAM 1:2023)

Building environment design - Embedded radiant heating and cooling systems - Part 3: Design and dimensioning - Amendment 1 (ISO 11855-3:2021/DAM 1:2023)

Umweltgerechte Gebäudeplanung - Flächenintegrierte Strahlungsheiz- und - kühlsysteme - Teil 3: Planung und Auslegung (ISO 11855-3:2021/DAM 1:2023)

Conception de l'environnement des bâtiments - Systèmes intégrés de chauffage et de refroidissement par rayonnement - Partie 3: Conception et dimensionnement - Amendement 1 (ISO 11855-3:2021/DAM 1:2023)

Ta slovenski standard je istoveten z: EN ISO 11855-3:2021/prA1

ICS:

91.140.10	Sistemi centralnega ogrevanja	Central heating systems
91.140.30	Prezračevalni in klimatski sistemi	Ventilation and air- conditioning systems

SIST EN ISO 11855-3:2021/oprA1:2023 en,fr,de

SIST EN ISO 11855-3:2021/oprA1:2023

iTeh STANDARD PREVIEW (standards.iteh.ai)

SIST EN ISO 11855-3:2021/oprA1:2023

https://standards.iteh.ai/catalog/standards/sist/f3a73ffe-921b-41dd-8baf-d1e8baba6dd4/sist-eniso-11855-3-2021-opra1-2023

DRAFT AMENDMENT ISO 11855-3:2021/DAM 1

ISO/TC 205

Secretariat: ANSI

Voting begins on: **2023-01-18**

Voting terminates on: 2023-04-12

Building environment design — Embedded radiant heating and cooling systems —

Part 3: Design and dimensioning

AMENDMENT 1

Conception de l'environnement des bâtiments — Systèmes intégrés de chauffage et de refroidissement par rayonnement —

Partie 3: Conception et dimensionnement

AMENDEMENT 1

(standards.iteh.ai)

ICS: 91.040.01

SIST EN ISO 11855-3:2021/oprA1:2023

https://standards.iteh.ai/catalog/standards/sist/f3a73ffe-921b-41dd-8baf-d1e8baba6dd4/sist-eniso-11855-3-2021-opra1-2023

This document is circulated as received from the committee secretariat.

THIS DOCUMENT IS A DRAFT CIRCULATED FOR COMMENT AND APPROVAL. IT IS THEREFORE SUBJECT TO CHANGE AND MAY NOT BE REFERRED TO AS AN INTERNATIONAL STANDARD UNTIL PUBLISHED AS SUCH.

IN ADDITION TO THEIR EVALUATION AS BEING ACCEPTABLE FOR INDUSTRIAL, TECHNOLOGICAL, COMMERCIAL AND USER PURPOSES, DRAFT INTERNATIONAL STANDARDS MAY ON OCCASION HAVE TO BE CONSIDERED IN THE LIGHT OF THEIR POTENTIAL TO BECOME STANDARDS TO WHICH REFERENCE MAY BE MADE IN NATIONAL REGULATIONS.

RECIPIENTS OF THIS DRAFT ARE INVITED TO SUBMIT, WITH THEIR COMMENTS, NOTIFICATION OF ANY RELEVANT PATENT RIGHTS OF WHICH THEY ARE AWARE AND TO PROVIDE SUPPORTING DOCUMENTATION.

ISO/CEN PARALLEL PROCESSING



ISO 11855-3:2021/DAM 1:2023(E)

iTeh STANDARD PREVIEW (standards.iteh.ai)

SIST EN ISO 11855-3:2021/oprA1:2023

https://standards.iteh.ai/catalog/standards/sist/f3a73ffe-921b-41dd-8baf-d1e8baba6dd4/sist-eniso-11855-3-2021-opra1-2023



COPYRIGHT PROTECTED DOCUMENT

© ISO 2023

All rights reserved. Unless otherwise specified, or required in the context of its implementation, no part of this publication may be reproduced or utilized otherwise in any form or by any means, electronic or mechanical, including photocopying, or posting on the internet or an intranet, without prior written permission. Permission can be requested from either ISO at the address below or ISO's member body in the country of the requester.

ISO copyright office CP 401 • Ch. de Blandonnet 8 CH-1214 Vernier, Geneva Phone: +41 22 749 01 11 Email: copyright@iso.org Website: www.iso.org

Published in Switzerland

Building environment design — Embedded radiant heating and cooling systems —

Part 3: **Design and dimensioning**

AMENDMENT 1

Foreword

Modify to the following:

The main changes compared to the previous edition are as follows:

- the Scope clause was modified, series-related information has been moved to the Introduction section;
- normative references were modified;
 A RD P REVEW
- informative references have been moved to the Bibliography;
- Annex A was added for the calculation of the thermal resistance of the insulating layers;
- the radiant system types have been redefined and figures are updated based on the amendment;
- Typing error in formula (24) was modified; 73 fle-921b-41dd-8baf-d1e8baba6dd4/sist-en-

2 Normative references

Modify to the following:

ISO 11855-2, Building environment design — Embedded radiant heating and cooling systems — Part 2: Determination of the design heating and cooling capacity

ISO 11855-5, Building environment design —Embedded radiant heating and cooling systems — Part 5: Installation

5 Radiant panel

5.1 Floor heating systems

5.1.4 Field of characteristic curves

Modify to the following:

The field of characteristic curves of a floor heating system with a specific pipe spacing *W* shall at least contain the characteristic curves for values of the thermal resistance of surface covering $R_{\lambda,B} = 0$, $R_{\lambda,B} = 0,05$, $R_{\lambda,B} = 0,10$ and $R_{\lambda,B} = 0,15$ (m²K/W), in accordance with ISO 11855-2 (see Figure 1). Values of $R_{\lambda,B} > 0,15$ (m²K/W) shall not be used if possible.

SIST EN ISO 11855-3:2021/oprA1:2023

ISO 11855-3:2021/DAM 1:2022(E)

5.1.5 Limit curves

Figure 1

Modify to the following:



- Y $q W/m^2$
- 1 limit curves
- 2 performance characteristic curves
- ^a Peripheral area.
- ^b Occupied area.

Figure 1 — Field of characteristic curves, including limit curves for floor heating, for constant pipe spacing

5.1.6 Downwards thermal insulation

Modify to the following:

In order to limit the heat flow through the floor towards the space below, the required back-side thermal resistance of the insulating layer $R_{\lambda,ins}$ shall be specified in the design to be not lower than the value in ISO 11855-5, 5.1.2.3.2.

For systems which have a flat insulating layer (system types I, II and IV in ISO 11855-1), the back-side thermal resistance of the insulating layer $R_{\lambda,ins}$ is calculated by Formula (7) where there is no stud. And the effective thickness of thermal insulating layer s_{ins} is identical to the thickness of the thermal

ISO 11855-3:2021/DAM 1:2022(E)

insulating panel and the effective thermal conductivity of the thermal insulation layer λ_{ins} is calculated by Formula (7) where there are studs.

$$R_{\lambda,\text{ins}} = \frac{s_{\text{ins}}}{\lambda_{\text{ins}}} \tag{7}$$

$$\lambda_{\rm ins} = \lambda_{\rm i} \, \frac{l_{\rm p} - l_{\rm ws}}{l_{\rm ps}} + \lambda_{\rm ws} \, \frac{l_{\rm ws}}{l_{\rm ps}} \tag{8}$$

where

- λ_i is thermal conductivity of the thermal insulation layer between the studs;
- λ_{ws} is thermal conductivity of the stud;
- $l_{\rm ps}$ is the distance between the studs (see Figure 2);
- $l_{\rm ws}$ is the thickness of the stud (see Figure 2).

Depending on the construction of the floor heating system, the effective thickness of thermal insulating layer s_{ins} and effective thermal conductivity of the thermal insulation layer λ_{ins} are determined differently.

For floor heating systems with flat thermal insulating panels of system types I in ISO 11855-1, the effective thickness of thermal insulating layer s_{ins} is identical to the thickness of the thermal insulation, and the effective thermal conductivity of the thermal insulation layer λ_{ins} is identical to the thermal conductivity of the thermal insulation layer 2]. For floor heating systems with thermal insulation panels with studs according to Annex A (system type I systems) (Figure A.1), only the flat part of the panel (without studs) shall be considered in the calculation of s_{ins} .

For the system with profiled thermal insulating panels of system type II in ISO 11855-1, Figure 3, the effective thickness of the insulating layer shall be determined by Formula (9).

$$s_{\rm ins} = \frac{s_{\rm h} \cdot (W - D) + s_{\rm l} \cdot D}{W}$$
(9)

For the system with the light wooden radiant panel on the joist of system type IV in ISO 11855-1, Figure 5, the effective thickness of thermal insulating layer s_{ins} is identical to the thickness of the thermal insulating panel, and the effective thermal conductivity of the thermal insulation layer λ_{ins} is:

$$\lambda_{\rm ins} = \lambda_{\rm i} \frac{l_{\rm p} - l_{\rm w}}{l_{\rm p}} + \lambda_{\rm w} \frac{l_{\rm w}}{l_{\rm p}} \tag{10}$$

where

- λ_i is thermal conductivity of the thermal insulation layer between the joists;
- λ_{w} is thermal conductivity of the joist;
- $l_{\rm p}$ is the distance between the joist (see Figure 5);
- $l_{\rm w}$ is the thickness of the joist (see Figure 5).

For system type IV systems with air cavities, see ISO 11855-2, Annexes C and E.

Figure 2

ISO 11855-3:2021/DAM 1:2022(E)



Key

Td

- D external diameter of the pipe
- In thermal insulation layer
- Pe pipes or electric cables
- Pt protection layer
- Sf surface layer
- St structural layer

STANDARD PREVIEW (standards.iteh.ai)

- SIST EN ISO 11855-3:2021/oprA1:2023
- s_u thickness of the layer above the pipe^{2/standards/sist/Ba73 fie-921b-41dd-8baf-d1e8baba6dd4/sist-en-}
 - thermal diffusion layer iso-11855-3-2021-opra1-2
- W pipe spacing

Figure 2 — Effective thickness and effective thermal conductivity of thermal insulating layer of flat thermal insulating panel — System types I

Figure 3



Figure 3 — Effective thickness and effective thermal conductivity of thermal insulating layer of flat thermal insulating panel — System type III

Figure 4

SIST EN ISO 11855-3:2021/oprA1:2023

ISO 11855-3:2021/DAM 1:2022(E)



Key

- thermal insulation layer In
- pipes or electric cables Pe
- protection layer Pt
- surface layer Sf
- structural layer St
- thickness of the layer above the pipe
- s_u thickness of heat conducting device
- \mathbf{s}_{wl} thermal conduction layer
- Тс
- thermal diffusion layer Td
- W pipe spacing

Figure 4 — Effective thickness and effective thermal conductivity of thermal insulating layer of profiled thermal insulating panel - System type II

Figure 5